PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16580
1.3 Title of PCN	SAMSUNG Foundry (Korea) STM32H74x & STM32H75x - product enhancements
1.4 Product Category	STM32H742x, STM32H743x, STM32H753x, STM32H750x, STM32H745x, STM32H755x, STM32H747x and STM32H757x
1.5 Issue date	2026-11-09

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like wafer edge region (Polyimide coverage or edge exclusion)	Samsung Foundry (Korea)

4. Description of change		
	Old	New
4.1 Description	Current STM32H74x and STM32H75x products - Samsung Foundry: revision 1 Reference Manuals current versions: - RM0433 (STM32H742/743/753 and STM32H750 Single core) version 8, Jan 2023 - RM0399 (STM32H745/755 and STM32H747/757 Dual Core) version 4, June 2023 ErrataSheet - ES0392 (STM32H742/743/753 and STM32H750 Single core) Rev 15 , September 2025 - ES0445 (STM32H745/755 and STM32H747/757 Dual Core) Rev 6 , September 2025	STM32H74x and STM32H75x products enhancement - Samsung Foundry: revision 6 New Reference Manual versions: - RM0433 (STM32H742/743/753 and STM32H750 Single core) new version 9, June 2026 - RM0399 (STM32H745/755 and STM32H747/757 Dual Core) new version 5, June 2026 ErrataSheet - ES0392 (STM32H742/743/753 and STM32H750 Single core) Rev 16 - ES0445 (STM32H745/755 and STM32H747/757 Dual Core) Rev 7
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement	

5. Reason / motivation for change	
5.1 Motivation	Improvements implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change	
6.1 Description	Traceability ensured by ST internal tools. Die revision visible on top marking is updated : - Samsung Foundry : revision from "1" to "6"

7. Timing / schedule	
7.1 Date of qualification results	2026-12-15
7.2 Intended start of delivery	2026-12-20
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	16580 MDRF-GPAM RER2403 - PCN16580 - Die 450 CSI Fix Samsung F M40 - Reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2026-11-09

9. Attachments (additional documentations)
16580 Public product.pdf 16580 MDRF-GPAM RER2403 - PCN16580 - Die 450 CSI Fix Samsung F M40 - Reliability plan.pdf 16580 _Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32H742VGT6	
	STM32H742VIT6	
	STM32H742ZGT6	
	STM32H743AII6	
	STM32H743IGT6	
	STM32H743IIK6	
	STM32H743IIT6	
	STM32H743VGT6	
	STM32H743VIH6	
	STM32H743VIT6	
	STM32H743VIT6TR	
	STM32H743XIH6	
	STM32H743XIH6TR	
	STM32H743ZGT6	
	STM32H743ZIT6	
	STM32H743ZIT6TR	
	STM32H745IIK6	
	STM32H745IIT6	
	STM32H745XGH6	
	STM32H745XIH3	
	STM32H745XIH6	
	STM32H745ZIT3	
	STM32H745ZIT6	
	STM32H747AII6	
	STM32H747IGT6	
	STM32H747IIT6	
	STM32H747XIH6	
	STM32H750IBK6	
	STM32H750IBK6TR	
	STM32H750IBT6	
	STM32H750VBT6	
	STM32H750VBT6TR	
	STM32H750XBH6	
	STM32H750ZBT6	
	STM32H753AII6	
	STM32H753IIK6	
	STM32H753IIT6	
	STM32H753VIH6	
	STM32H753VIT6	

	STM32H753VIT6TR	
	STM32H753XIH6	
	STM32H753XIH6TR	
	STM32H753ZIT6	
	STM32H755IIK3	
	STM32H755IIK6	
	STM32H755IIT3	
	STM32H755IIT6	
	STM32H755XIH3	
	STM32H755XIH6	
	STM32H755ZIT3	
	STM32H755ZIT6	
	STM32H757IIT6	
	STM32H757XIH6	
	STM32H757XIH6A	
	STM32H743BGT6	
	STM32H743BIT6	
	STM32H745BIT6	
	STM32H747BIT6	
	STM32H753BIT6	
	STM32H755BIT3	
	STM32H755BIT6	
	STM32H757BIT6	

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